

low thermal expansion prepgs prepns e.g. for PCB's - by filling inorganic particles into monofilament strand, impregnated resin varnish and drying

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Patent Family:

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JP 9003217	A	19970107	JP 95151850	A	19950619	199711 B

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Patent Details:

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Abstract (Basic): JP 9003217 A

Prepn. of reinforcing material (A) comprises filling 1-30 pts.wt. inorganic particles (A1) with average particle size 1,000 nm or less into 100 pts. wt. of strand (A2) composed of monofilaments. (2) impregnating resin varnish (B) into (A) under 1-300 Torr, and (3) drying.

USE - (I) is useful as material for prepn. of composite materials e.g. PC substd.

ADVANTAGE - (I) gives composite materials having small coefficient of thermal expansion and good soldering resistance.

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Title Terms: LOW; THERMAL; EXPAND; PREPREG; PREPARATION; PCB; FILL; INORGANIC; PARTICLE; MONOFILAMENT; STRAND; IMPREGNATE; RESIN; VARNISH; DRY

Derwent Class: A85; L03; V04; X12

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